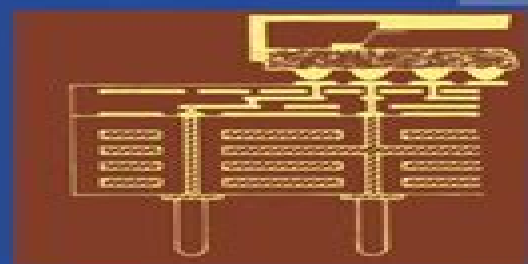
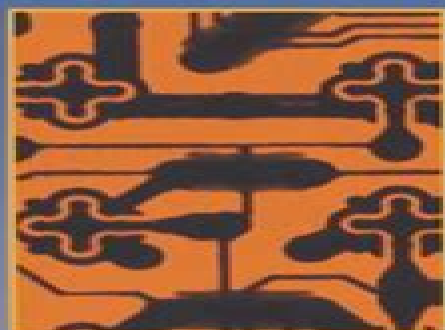


# MICROELECTRONICS PACKAGING HANDBOOK

## *Semiconductor Packaging*

PART II



**Second Edition**

Edited by  
**Rao R. Tummala**  
**Eugene J. Rymaszewski**  
**Alan G. Klopfenstein**

# Microelectronics Packaging Handbook Part 2

## Semiconductor Packaging Pt 1

**Rao Tummala, Eugene J.**  
**Rymaszewski, Alan G. Klopfenstein**



## **Microelectronics Packaging Handbook Part 2 Semiconductor Packaging Pt 1:**

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